



# COTS Testing

## EIA to 55302

INNOVATIVE TECHNOLOGIES • SUDDEN SERVICE • GLOBAL REACH

- Samtec Introduction
    - Who we are
  - Testing Standards
    - SET, 55302, EAI
  - GAP Analysis
    - What really sets them apart?
  - Conclusion/Q&A
- Your Presenter
    - John Riley, [John.Riley@samtec.com](mailto:John.Riley@samtec.com), Sr. Technical Marketing Engineer
      - John Riley is senior technical marketing engineer at Samtec. For more than 22 years, he has defined, designed, developed, and tested high-performance copper, RF and optical interconnect for a number of rugged and embedded computing applications. Additionally, he and his wife champion STEM education, advanced manufacturing techniques and community outreach via their non-profit maker space. John holds a bachelor's degree in mechanical engineering from the University of Louisville.
  - Your Contacts
    - Chuck Grantz, [chuck.grantz@Samtec.com](mailto:chuck.grantz@Samtec.com), Mil/Aero Industry Mgr.
    - Evan Baumer, [evan.baumer@samtec.com](mailto:evan.baumer@samtec.com), Mil/Aero Testing Coordinator
    - Chris Wade, [chris.wade@samtec.com](mailto:chris.wade@samtec.com), Rugged/Power Product Mgr.
  - Additional Information
    - Visit [www.samtec.com/milaero](http://www.samtec.com/milaero)
    - E-mail [MILITARY@samtec.com](mailto:MILITARY@samtec.com)
    - Website <https://www.samtec.com/standards/>

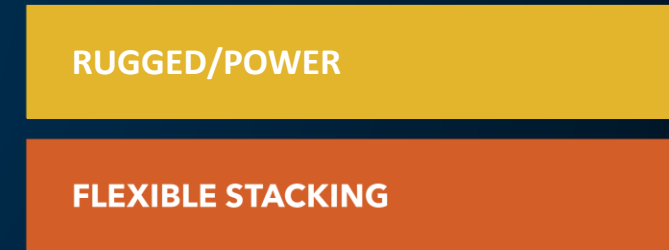


# BUSINESS MODEL

## SILICON-TO-SILICON



## CORE BOARD-TO-BOARD

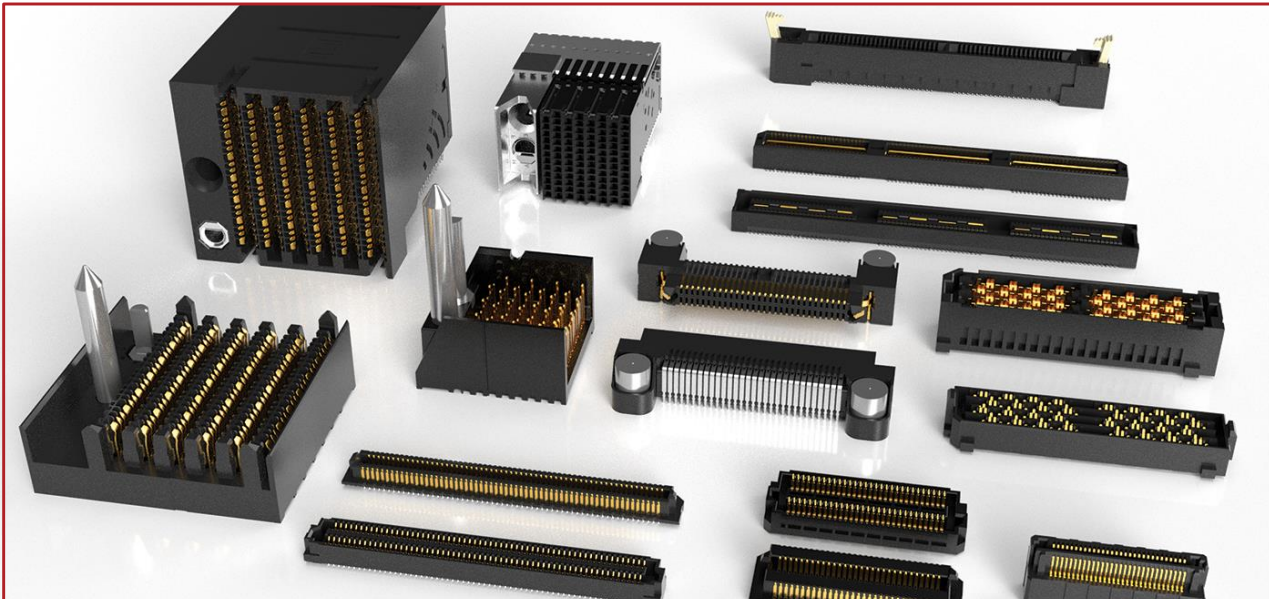


## SUDDEN SERVICE



## GLOBAL INFRASTRUCTURE





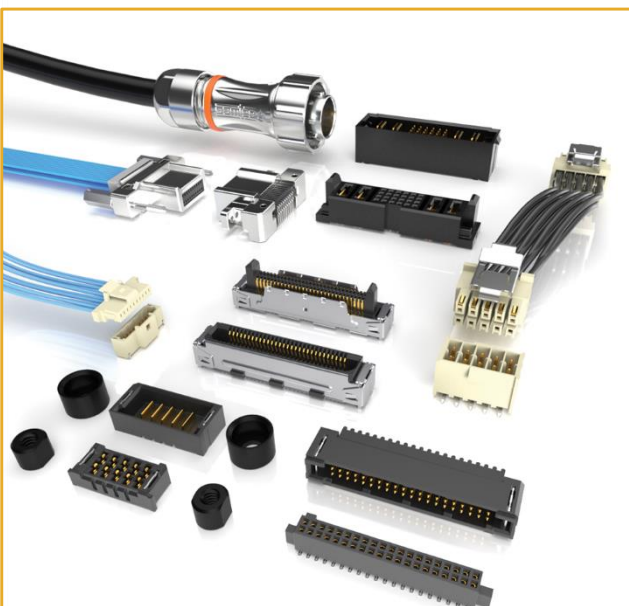
## HIGH-SPEED BOARD-TO-BOARD

OPEN-PIN-FIELD ARRAYS | GROUND PLANE STRIPS | ULTRA-MICRO | BACKPLANE



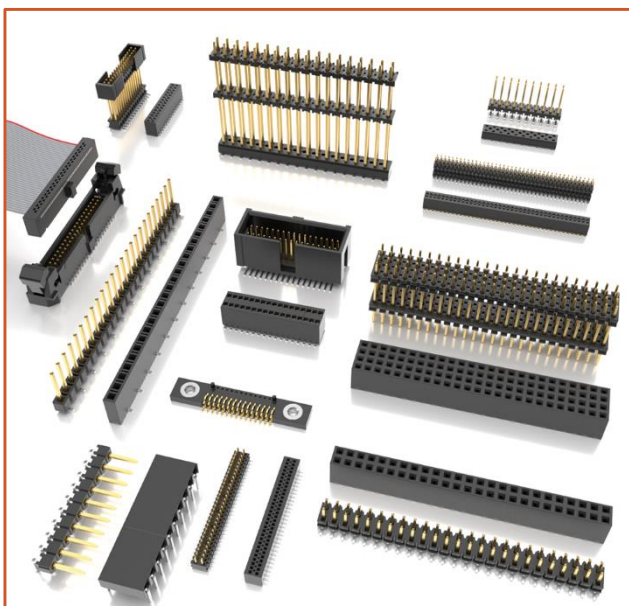
## HIGH-SPEED CABLE

FLYOVER® | MID-BOARD & PANEL | BACKPLANE | MICRO COAX & TWINAX



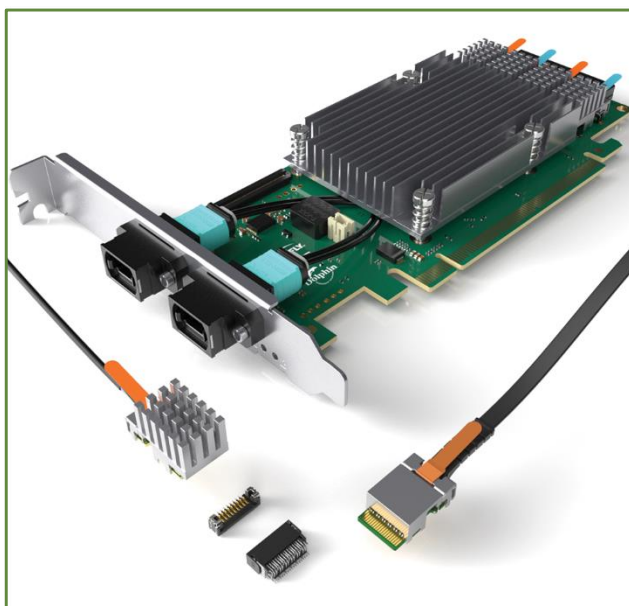
## RUGGED/POWER

RUGGED BOARD-TO-BOARD | BLADE POWER  
MICRO DISCRETE WIRE | RUGGED I/O | ULTRA RUGGED



## FLEXIBLE STACKING

LOW PROFILE | PASS-THROUGH | ONE-PIECE  
SKYSCRAPERS | SHROUDED HEADERS | IDC SYSTEMS



## OPTICS

MICRO FLYOVER SYSTEMS™ | EXTENDED TEMP  
PCI EXPRESS®-OVER-FIBER



## RF

PRECISION RF | 50 Ω SOLUTIONS  
75 Ω SOLUTIONS | ORIGINAL SOLUTIONS



# GLOBAL SUPPORT NETWORK

With more than **25,000+** direct customers spanning all industries, Samtec **serves** well-known **global tech giants**, **small start-ups**, and **everyone** in between.



**13** DESIGN CENTERS

**14** OPERATION FACILITIES

**24** SALES OFFICES

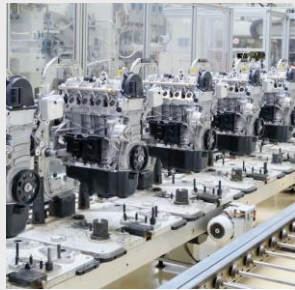
**125+** SALES SUPPORT

**6.5K+** GLOBAL EMPLOYEES

Samtec Confidential

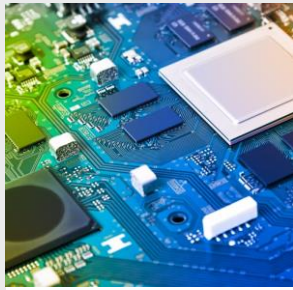
# MARKETS SERVED | PERCENT OF SALES

Based on 2023 Sales



INDUSTRIAL

22%



COMPUTER/  
SEMICONDUCTOR

22%



DATAKOM

13%



MEDICAL

13%



INSTRUMENTATION

9%



AERO/  
DEFENSE

11%



AUTO/TRANS/  
TELEMATICS

7%



CONSUMER

3%

**Customer Base of 50,000**  
25,000 (Direct) + 25,000 (Digital)



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# GAP Analysis Overview

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- Little to no GAP when looking at the testing method.
- Frequency is a GAP relative to traditional DQT.  
DQT during design, 55302 each lot
- Test reports and tracking may be a GAP relative to traditional DQT
- Capacity of conducting the test at the manufacturing site is a GAP
  - COTS manufactures are not traditionally Mil-Spec only assembly house
  - May require a secondary test house for up screening

# Testing Standards

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- Traditional DQT
  - All Samtec series undergo Design Qualification Testing (DQT). This includes Normal Force, Thermal Aging, Mating/Unmating/Durability, IR/DWV, Current Carrying Capacity (CCC), and Mechanical Shock/Random Vibration/LLCR and Event Detection.
- SET
  - Severe Environment Testing (SET) is a Samtec initiative to test certain products beyond typical industry standards and specifications, many of which are common requirements for harsh environment applications/industries.
- MIL-DTL-55302 Lot Screen Testing (EEE-INST-002)
  - Military specification detailing the requirements for miniature, high-density, electrical connectors used in electronic systems. The specification covers various aspects including design, materials, performance, and testing criteria to ensure consistency and interoperability across different manufacturers and applications within the military domain.



# Traditional DQT

- Traditional DQT
  - Normal Force
  - Thermal Aging
  - Mating/Unmating/Durability
  - IR/DWV
  - Current Carrying Capacity (CCC)
  - Mechanical Shock/Random Vibration
  - LLCR
  - Event Detection.
- The EIA (Electronic Industries Alliance) developed standards for electronic connectors to ensure compatibility, reliability, and performance across various electronic devices and systems. Here's a brief overview of some key aspects of EIA test standards for electronic connectors:
  - Physical Dimensions
  - Electrical Performance
  - Mechanical Durability
  - Environmental Testing
  - Material and Finish
  - Interoperability

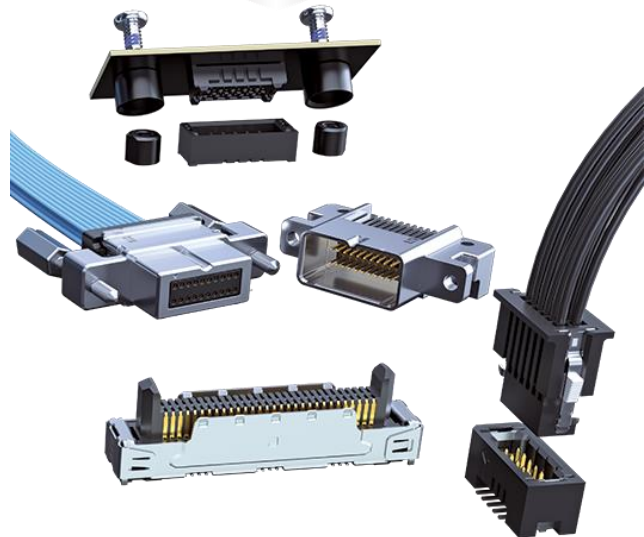
Samtec interconnects are subject to a wide variety of standard test procedures that push the industry limits to help ensure quality and durability in any application.

Severe Environment Testing includes additional testing for interconnect systems that will be used in extreme or harsh environment applications:

- **VITA 47.1 Module Insertions**
- **VITA 47.3 Humidity**
- **VITA 47.1 Operating Shock Class OS2**
- **VITA 47.1 Vibration Class VS3**
- **Exceeds VITA 47.1 Temperature Cycling Class C4**
- **Exceeds VITA 47.1 Non-Operating Class C4**
- **VITA 47.1 Electrostatic Discharge Resistance**
- **Exceeds VITA 47.1 Altitude for DWV**



SET products are approved for Class D missions that require high-reliability, quick-turn and cost-effective solutions for LEO satellites, SmallSats, CubeSats and other space exploration applications.



## 2024: EXPANDING THE REACH OF SET



- 55302**
- Salt Spray
  - Thermal Shock
  - Enhanced S&V
  - Lot based Inspection

*“Meets or exceeds MIL-DTL-55302 testing!”*





# MIL-DTL-55302 LIKE LOT SCREENING TEST

- MIT-DTL-55302 like conformance inspection
  - Modified for Samtec connectors
    - Mate/Unmate/Durability
    - IR/DWV
    - Solderability
  - Group A, Group B, Group C
  - Test reports for shipped with every order

**TEST FLOW**

**TEST SEQUENCE RESULTS**

Test Description	Group	Test Standard	Test Description	Qty	Result	
Mating / Unmating	1	EIA-364-23	LLCR	8	Report Min/Max/Avg (See Below)	
		EIA-364-13	M/UM Forces Initial	8	Report Min/Max/Avg (See Below)	
		EIA-364-13	M/UM Forces After	8	Report Min/Max/Avg (See Below)	
IR/DWV	2	Visual				
		Mechan				
		Inspecti				
		Mechan				
Solderability	1	EIA-364-1				
		EIA-364-2				
		EIA-364-3				

**DATA SUMMARIES:**

**LLCR**  
CR-860304

**LLCR Results for Test MUD**  
Series: MAP-230211/MAP-230212

**Mating/Unmating**

Sample	Initial	Final
1	2.50	2.00
2	3.19	2.47
3	2.30	2.18
4	2.87	2.13
5	3.58	2.86
6	3.10	2.89
7	2.97	2.89
8	3.18	2.92

**CERTIFICATION**

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to ISO 9002 and ANSI/NSL 2540-1, as applicable.

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**APPLICABLE DOCUMENTS**

Standards: EIA Publication 364.

**TEST SAMPLES AND PREPARATION**

- 1) All materials were manufactured in accordance with the applicable product specification.
- 2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
- 3) After soldering, the parts to be used for LLCR and IR, DWV testing were cleaned according to T.LW10001.
- 4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
- 5) The automated procedure is used with aqueous compatible soldering materials.
- 6) Parts not intended for testing LLCR and IR, DWV are visually inspected and cleaned if necessary.
- 7) Any additional preparation will be noted in the individual test sequences.
- 8) Solder Information: Tin-Lead
- 9) Re-Flow Time/Temp:
- 10) All parts were taken from the production run of parts.
- 11) Samtec Test PCBs used as per Samtec specification.

**ATTRIBUTE DEFINITIONS**

The following is a brief, simplified description of attributes.

**LLCR:**  
Reference document: EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.

**MATING/UNMATING:**  
Reference document: EIA-364-13E, Mating and Unmating Force Test Procedure for Electrical Connectors and Sockets

**DIELECTRIC WITHSTANDING VOLTAGE (DWV):**  
Reference document: EIA-364-20, Withstanding Voltage Test Procedure for Electrical Connectors.

**INSULATION RESISTANCE (IR):**  
Reference document: EIA-364-21, Insulation Resistance Test Procedure for Electrical Connectors.

**SOLDERABILITY:**  
Reference document: J-STD-002D, Method A, Solderability Test for Component Leads, Terminations, Lugs, Terminals and Wires

# GAP Analysis

MIL-DTL-55302 Conformance Inspection Requirements			Samtec Lot and Qual Conformance		
Group A (Each Lot)			Samtec Lot Sample Screening (Each Lot)		
Requirement	Method		Requirement	Method	Samtec Comment
Visual and Mechanical inspection	Clause 4.5.1		Visual and Mechanical inspection	Samtec Standard	Visual and Dimensional inspection per product drawing and visual inspection. Microscope is used.
Contact Engagement and Separation Forces	Claus 4.5.3: EIA-364-37, Method A.		Mating/Unmating Forces	EIA-364-13	EIA-364-37 focuses on individual pins that are crimped and inserted. PCB mounted connectors would be better represented by EIA-364-13. Does Not Apply.
Interchangeability	Clause 4.5.1.2		N/A	N/A	Samtec publishes mateable products online. We consider mate/unmate as evidence.

# GAP Analysis

Group B (Every 24 months)			Samtec Lot Sample Screening (Each Lot)		
Requirement	Method		Requirement	Method	Samtec Comment
Mating and Unmating	Clause 4.5.4: After 3 unmonitored cycles of insertion and withdrawal, the force required to fully insert and withdraw a plug from the receptacle shall be measured.		Mating/Unmating	EIA-364-13	EIA-364-13, Measure force necessary to mate specimens at a maximum rate of 12.7 mm [.5 in] per minute
Low Level Circuit	Clause 4.5.12: EIA-364-23		LLCR	EIA-364-23	No Comment
Contact Resistance	Clause 4.5.5: EIA-364-06		LLCR	EIA-364-23	55302 references AWG to determine test criteria. These are not crimp contact connectors. LLCR is low level, therefore, would be a better test bc it would be more sensitive to changes in resistance. Does Not Apply.
Insulation Resistance	Clause 4.5.8: EIA-364-21		Insulation Resistance	EIA-364-21	Samtec checks pin to pin and row to row.
Dielectric Withstanding Voltage (Sea Level)	Clause 4.5.7.1: EIA-364-20, Method A		Dielectric Withstanding Voltage	EIA-364-20	No Comment
Crimp Tensile Strength	Clause 4.5.20		N/A	N/A	Applicable to crimp contacts only. Does Not Apply.

# GAP Analysis

Group C (Every 36 months)			Samtec Qualification Conformance Inspection (As Requested)		
Subgroup 1					
Requirement	Method		Requirement	Method	Samtec Comment
Visual and Mechanical	Clause 4.5.1		Visual and Mechanical inspection	Samtec Standard	Visual and Dimensional inspection per product drawing and visual inspection. Microscope is used.
Oversized Pin Exclusion	Clause 4.5.2		N/A	N/A	55302 references circular contacts. Samtec pins are stamped with micron level tolerances. Does Not Apply.
Contact Engagement and Separation Forces	Clause 4.5.3: EIA-364-37, Method A.		Mating/Unmating Forces	EIA-364-13	EIA-364-37 focuses on individual pins that are crimped and inserted. PCB mounted connectors would be better represented by EIA-364-13. Does Not Apply.
Contact Retention	Clause 4.5.6		N/A	N/A	According to MIL-DTL-55302, this does not apply to mounted PCB connectors. Does Not Apply.
Dielectric Withstanding Voltage (High Altitude)	Clause 4.5.7.2: EIA-364-20, Method A		DWV (Altitude)	EIA-364-20	Samtec to determine the altitude/pressure.
Contact Life	Clause 4.5.9		Extended Life Testing Cycling	Multiple	500 mating cycles with Humidity, Thermal Shock and Mate/Unmate.
Contact Resistance	Clause 4.5.5: EIA-364-06		Current Carry Capacity	EIA-364-70	Above is why Samtec feels Contact Resistance, as detailed in 55302, does not apply. For Qual conformance, Samtec provides current carrying capacity as this, along with LLCR, can indicate contact resistance performance.

# GAP Analysis Overview

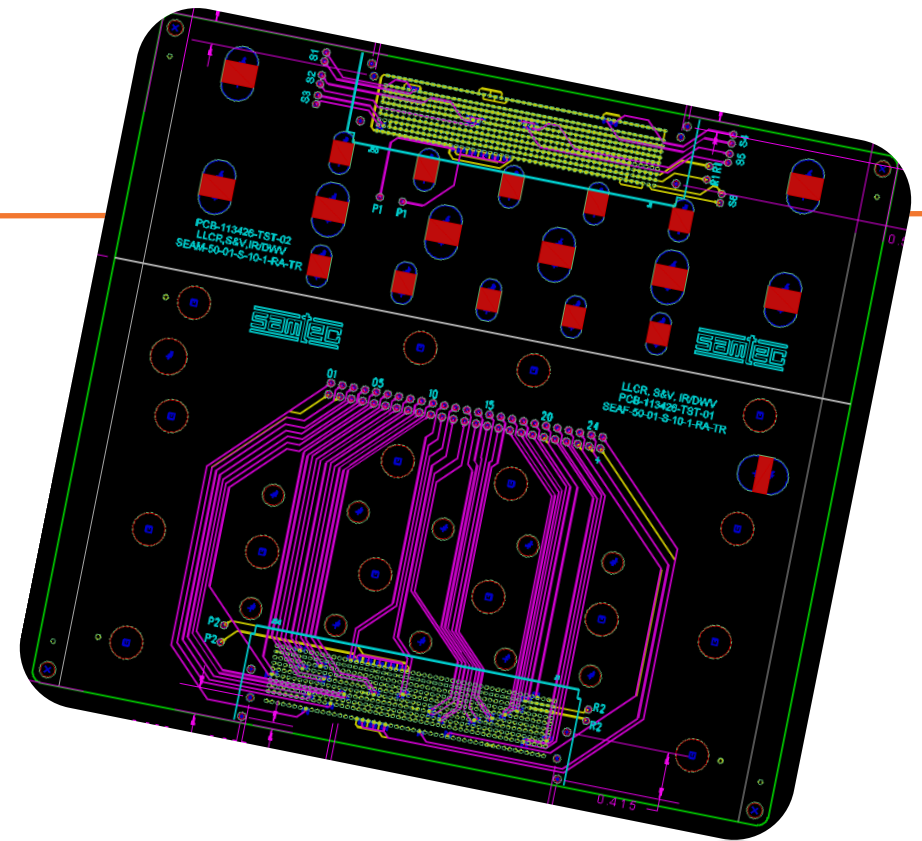
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# Observations

- Many test standards work together or reference each other.
- When looking for COTS components review the actual requirements needed.
- Time to market/test completion can be lengthy depending on information that can be shared with the test houses.
- 100% electrical testing may need to evolve.



Cross Reference of EIA-364 Procedures and MIL-STD-1344 Methods

TEST	EIA-364 Procedure	MIL-STD-1344 Method
Mating and unmating forces	EIA-364-13	MIL-STD-1344 Method 2013
Temperature life with or without electrical load	EIA-364-17	MIL-STD-1344 Method 1005
Withstanding voltage	EIA-364-20	MIL-STD-1344 Method 3001
Insulation resistance	EIA-364-21	MIL-STD-1344 Method 3003
Low level contact resistance	EIA-364-23	MIL-STD-1344 Method 3002
Salt spray	EIA-364-26	MIL-STD-1344 Method 1001
Mechanical shock (specified pulse)	EIA-364-27	MIL-STD-1344 Method 2004
Vibration	EIA-364-28	MIL-STD-1344 Method 2005
Humidity	EIA-364-31	MIL-STD-1344 Method 1002
Thermal shock (temperature cycling)	EIA-364-32	MIL-STD-1344 Method 1003
Contact engagement and separation force	EIA-364-37	MIL-STD-1344 Method 2014

# Supporting Information



## OUTGASSING FAQs GUIDE



As Commercial Off the Shelf (COTS) products continue to be used within Military / Aerospace, Space, Industrial, Transportation, Automotive, and Medical applications, it is important to understand how those products will respond. A low outgassing component is needed in these environments to prevent damage to sensitive electronics, lenses (optics), mirrors and windows.

### What is Outgassing?

Outgassing is the process in which a non-metallic material such as a polymer, adhesive, rubber, or potting compound / epoxy will release a gas when exposed to heat and/or a vacuum. A NASA-developed test standard, ASTM E595-77/84/90, is used to determine how much volatile content is contained in material sample; for a product to be qualified for space flight, it must pass this test standard.

### How is Outgassing Tested?

Samtec utilizes NASA outgassing data to determine if certain products, such as our high-reliability Tiger Eye™, high-speed Q Series® and rugged Edge Rate® connectors, meet these requirements. NASA uses the ASTM E595-77/84/90 test, and the steps in this test include:

- Exposure of the parts to 25 °C at a 50% Relative Humidity for 24 hours
  - Products are then weighed
  - Exposure in a chamber at 125 °C for 24 hours at a vacuum no less than 5x10<sup>-5</sup> torr
    - Chamber contains a cooling collector plate at 25 °C to collect gas condensate
  - Products are then weighed again with the collector plate
- The weight of the sample is taken before and after the experiment and the materials are considered to have passed if the total mass lost (TML) and the collected volatile condensable materials (CVCM) are below 1.0% and 0.10% respectively. NASA outgassing data can be found at [outgassing.nasa.gov](http://outgassing.nasa.gov).



Micro Rugged Connectors & Cables • High-Speed Mezzanine • High-Density Arrays • Micro Pitch Connectors • Micro Power Discrete Wire & IDC • High-Speed Hermaphroditic Strips • High-Speed Edge Card Sockets

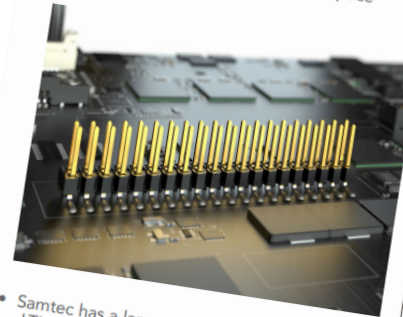


## TIN-LEAD PLATING

Commercial Off-the-Shelf Products are a vital part of the Military / Aerospace and Space industries. Tin-Lead plating is required in many applications to prevent electrical damage.

### Why use Tin-Lead Plating?

- Tin-Lead Plating has advantages over Lead-Free plating including lower processing temperatures, easier field repair, and no issues with Tin whiskers. For these reasons, Samtec still offers many series with Tin-Lead plating options for Military / Aerospace customers.



- Samtec has a large offering of products with -LTL (10 μ" of Gold in the contact area with Tin-Lead on the tails) and -STL (30 μ" of Gold in the contact area with Tin-Lead on the tails). May require certain pin/row count, stack heights or orientations.
- Samtec can also offer non-standard plating options for almost all of our series through Application Specific Products (ASP). Please contact [asp@samtec.com](mailto:asp@samtec.com) for more information.

Product Series	Plating Type	Product Series	Plating Type
ADF6	STL	SEAM	STL
ADM6	STL	SEAM8	STL
BCS	LTL	SFM	STL
CLP	LTL, STL	SFMC	STL
DW	STL	SFMH	LTL, STL
ERF8	STL	SOLC	STL
ERM8	STL	SQT	STL
EW	STL	SQW	STL
FSH	STL	SSM	STL
FSI	LTL, STL	SSQ	STL
FTSH	LTL, STL	SSW	STL
HLE	STL	TFM	STL
HMTSW	STL	TFML	STL
HTSW	LTL, STL	TLW	STL
ICF	STL	TOLC	STL
IPL1	STL	TSM	STL
LSHM	STL	TSS	STL
MOLC	STL	TSSH	STL
MTSW	STL	TSW	STL
QSE	LTL, STL	TW	LTL, STL
QSS	STL	UCC8	STL
QTE	STL	YTE	STL
QTS	STL	YTW	LTL, STL
RSM	STL	ZSS	STL
SEAF	STL	ZW	STL

For more information about military / aerospace offerings please contact [military@samtec.com](mailto:military@samtec.com)

# Questions

- Your Presenter

- John Riley, [John.Riley@samtec.com](mailto:John.Riley@samtec.com), Sr. Technical Marketing Engineer
  - John Riley is senior technical marketing engineer at Samtec. For more than 22 years, he has defined, designed, developed, and tested high-performance copper, RF and optical interconnect for a number of rugged and embedded computing applications. Additionally, he and his wife champion STEM education, advanced manufacturing techniques and community outreach via their non-profit maker space. John holds a bachelor's degree in mechanical engineering from the University of Louisville.

- Your Contacts

- Chuck Grantz, [chuck.grantz@Samtec.com](mailto:chuck.grantz@Samtec.com), Mil/Aero Industry Mgr.
- Evan Baumer , [evan.baumer@samtec.com](mailto:evan.baumer@samtec.com), Mil/Aero Testing Coordinator
- Chris Wade, [chris.wade@samtec.com](mailto:chris.wade@samtec.com), Rugged/Power Product Mgr.

- Additional Information

- Visit [www.samtec.com/milaero](http://www.samtec.com/milaero)
- E-mail [MILITARY@samtec.com](mailto:MILITARY@samtec.com)
- Website <https://www.samtec.com/standards/>



The logo features the word "samtec" in a bold, orange, sans-serif font. The letter 't' is taller than the others and has a vertical stem that extends below the baseline. The word is centered between two horizontal white bars, one above and one below. The background is dark blue with abstract, glowing orange and white light trails.

**samtec**

SUDDEN SERVICE®



# ABOUT US

Founded in 1976, Samtec is much more than just another connector company, we put people first with a commitment to exceptional service and quality products. We believe that taking care of our customers and our employees is paramount in how we approach our business. This belief is deeply ingrained throughout Samtec and means that you can expect **exceptional service** coupled with **technologies** that take the industry further faster.

## GLOBAL REACH



HEADQUARTERS  
**NEW ALBANY, IN**  
USA

**40** LOCATIONS

**125+** COUNTRIES SERVED

**6,500+** EMPLOYEES

PRIVATELY  
**OWNED COMPANY**

## SUDDEN SERVICE



MORE THAN 200k PART NUMBERS SHIP IN 1 DAY



24-HOUR FREE SAMPLES



2 DAYS TRANSIT TO ALL MAJOR MARKETS



**#1** CONNECTOR MANUFACTURER

## INDUSTRY UPDATE

SALES GROWTH (10-year span)

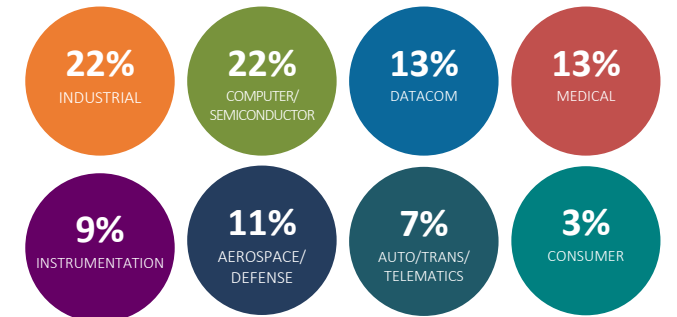
**SAMTEC**



**INDUSTRY**



MARKETS SERVED



# SUDDEN SERVICE<sup>®</sup>

Innovative Programs & Systems Enable **Deliveries in Days**, Not Weeks..

**Reserve**<sup>®</sup>  
SHIPS TOMORROW

MORE THAN 200k PART  
NUMBERS SHIP IN 1 DAY

**24HOUR**  
SUDDEN SAMPLE<sup>™</sup>

24-HOUR  
FREE SAMPLES

**2DAYS**  
WORLD DIRECT<sup>™</sup>

2 DAYS TRANSIT TO  
ALL MAJOR MARKETS

## 24/7 WORLDWIDE ACCESS

Samtec is the Electronics Industry's **Service** & **Technology** Leader.

### Technical Support

Signal Integrity Group: [sig@samtec.com](mailto:sig@samtec.com)

Application Support Group: [asg@samtec.co](mailto:asg@samtec.co)

Interconnect Processing Group: [ipg@samtec.com](mailto:ipg@samtec.com)

### Supply Chain Support

MySamtec<sup>™</sup> Real-Time Account Access: [account.samtec.com](https://account.samtec.com)

Personal Account Managers & CSRs: [ecustomerservice@samtec.com](mailto:ecustomerservice@samtec.com)

Upfront, Aggressive 24-Hour Quotes: [pricing@samtec.com](mailto:pricing@samtec.com)



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# SUDDEN SERVICE®

www.SAMTEC.com

Samtec has developed innovative search, design, and validation tools to help customers quickly and easily find the right solution. Search by product name, characteristics, pictures, or build an assembly by entering physical specifications.



## Online Tools

FIND, DESIGN & VALIDATE YOUR SOLUTION

### Solutionator®

DESIGN IN A MINUTE

Quickly build mated connector sets and cable assemblies using a wide variety of user-defined search parameters and filters.

### Picture Search

VISUALLY FIND YOUR SELECTION

Browse through Samtec's most popular products to find the ideal solution for your application. Visit [samtec.com/picturesearch](https://www.samtec.com/picturesearch).



## Downloads

3D MODELS, SPECS, PRINTS & MORE

### 3D Models

QUICK DOWNLOADS

Quickly configure, preview and download models in more than 150 different formats, including AutoCad, Solid Edge, Inventor and many more.

**mySAMTEC™**  
account.samtec.com

Samtec's user-friendly eCommerce platform allows you to quickly and easily check product availability and pricing, as well as place and manage your orders online.



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# 3D Models

## QUICK DOWNLOADS

Samtec 3D Models are accurate to the best of our knowledge and are provided as informational in nature. However due to technical progress, products are subject to change without notice. Please reference the product print for the most current and up-to-date information for this product.

TRY IT HERE

[samtec.com/3DMODELS](https://samtec.com/3DMODELS)

Number of Positions	025
Lead Style	-05.0 = 5mm (-5.0 f)
Plating	-L: 10 µ" Light Selec
Differential Pair (Hot Swap)	Not Selected
Differential Pair with Extended Guide Posts	Not Selected
Differential Pair with Extended Guide Post Shield	Not Selected
Latches	Not Selected
Shield Option	Not Selected
Extended Guide Posts	Not Selected
Extended Guide Post Shield	Not Selected
Polyimide Film Pad	Not Selected
Packaging Option	Tray
Part Number	ERM8-025-05.0-L-DV
Lead Style Note	For EGPS-K-TR combinations leave the zero off the front of the lead style callout
Number of Rows	-DV: Double Vertical

powered by PARTSolutions®



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### Features

- Rugged Edge Rate® contact
- Smooth broad milled contact surface for increased wear life
- 56 Gbps PAM4 performance
- SET Qualified Product: visit [samtec.com/SET](https://samtec.com/SET) for more

[Read More](#)

### Part Number

ERM8-025-05.0-L-DV

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